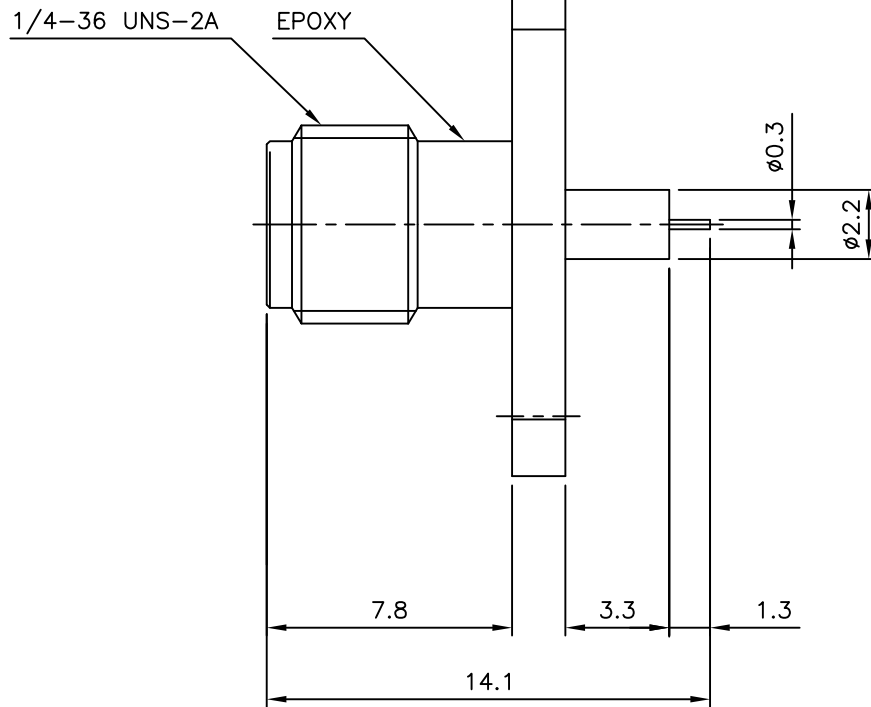


A

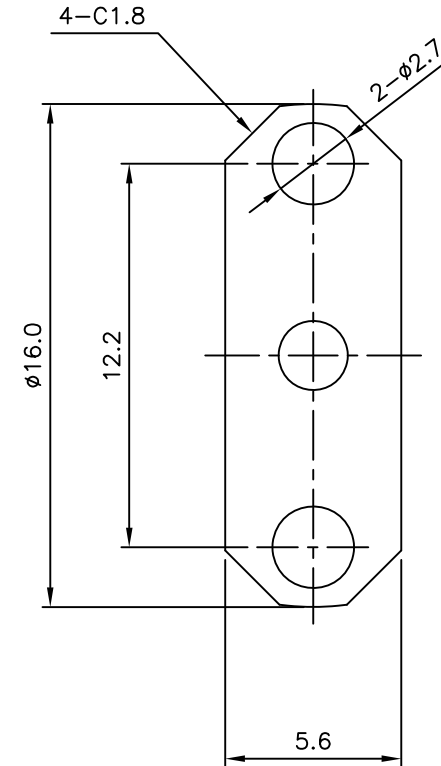
B

C

D



REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			
1	작업성 개선	Y.H.SON	B.H.AHN	2004.04.02.
2	작업성 개선 (에폭시 작업시 밀링 보완 납시턱 추가)	I.C.KIM		2021.10.29.
3	EPOXY 작업 후 핀 회전 방지로 인한 널링 추가	S.Y.EUN	S.H.KIM	2022.11.01.



3	INSULATOR	1	TEFLON		DIN01090-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT01163-5/1
1	BODY	1	SUS	Passivate	DBD01558-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2022. 11. 01.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY	S.H.KIM			
MATERIAL _____		CHECKED BY	TITLE SMA50 SOLDER END JS-2H			
		DRAWN BY				S.Y.EUN
FINISH _____	SCALE 5/1	UNIT mm		A4	DWG NO. CN00899-7/1	
					REVISION 3	SHEET 1 of 1

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